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ABSTRACT OF THE DISCLOSURE

After conductive patterns are formed on the conductive foil every block by employing isolation trenches, conductive plating layers are arranged selectively on the conductive patterns. Therefore, it is possible to accomplish the circuit device manufacturing method by which the die bonding of the circuit elements can be applied stably and the wire bonding can also be applied stably and which can fit to the mass-production while saving the resource.

RECORDED IN 35MM MICROFILM